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PPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO	
09/923,725	08/06/2001	Gregory J. Goldspring	LAM2P267A	1734	
25920	7590 04/19/2005		EXAMINER		
MARTINE PENILLA & GENCARELLA, LLP			AHMED, SHAMIM		
710 LAKEW	AY DRIVE				
SUITE 200		ART UNIT	PAPER NUMBER		
SUNNYVAL	LE, CA 94085	1765			
			DATE MAILED: 04/10/2004	_	

Please find below and/or attached an Office communication concerning this application or proceeding.

		Applicati	on No.	Applicant(s)	
<u></u>		09/923,7	25	GOLDSPRING E	T AL.
Office Action Summar		Examine	r	Art Unit	
		Shamim A		1765	
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	ecification is objected to by the	he Evaminer			
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* See the	attached detailed Office action	on for a list of the cert	tified copies not red	ceived.	
Attachment(s)					
	rences Cited (PTO-892)		4) Interview Sum	nmary (PTO-413)	
2) 🔲 Notice of Drafts	sperson's Patent Drawing Review (Paper No(s)/M	fail Date	
	sclosure Statement(s) (PTO-1449 o	r PTO/SB/08)	5)	mal Patent Application (P1	O-152)
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Art Unit: 1765

DETAILED ACTION

Response to Arguments

1. Applicant's arguments with respect to claims 1-3,16-19 have been considered but are most in view of the new ground(s) of rejection.

- 2. Applicants argue that Graza et al require the second layer to be patterned and thereby does not teach a non-patterned second layer.
- 3. In response, examiner states that the argument is not persuasive because Graza et al teach a second layer 162 is initially formed over a semiconductor substrate (160), which second layer is non-patterned (see col.7, lines 27-42 and figure 5a).

Claim Rejections - 35 USC § 112

4. The following is a quotation of the first paragraph of 35 U.S.C. 112:

The specification shall contain a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the same and shall set forth the best mode contemplated by the inventor of carrying out his invention.

5. Claims 1-3,16-19 are rejected under 35 U.S.C. 112, first paragraph, as failing to comply with the written description requirement. The claim(s) contains subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention. Claim 1 is amended in line 5, to incorporate the limitation of "a **non-patterned** second layer" is not describe in the specification. It is noted that a negative limitation should have express disclosure in the specification. See MPEP 2173.05(i).

Art Unit: 1765

Claim Rejections - 35 USC § 102

6. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- (e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.
- 7. Claims 1,3 and 16-18 are rejected under 35 U.S.C. 102(e) as being anticipated by Garaza et al (6,081,659) as evidenced by Rahman et al (5,521,052).

Garaza et al disclose a simulation process, wherein a product comprises a support layer of a semiconductor substrate (160), which resembles the claimed first layer, upon which a second layer of liquid photoresist composition layer (162), which is composed of a mixture of multiple material such as solvent and photoresist material, which second layer is formed on the support layer and the product is capable of simulating (col.7, lines 1-4 and lines 30-45).

Garaza et al inherently teach that the photoresist material includes metal ions such as copper, as evidenced by Rahman et al (col.1, lines 10-22 and col.3, lines 8-12).

Therefore, Garaza et al inherently teach that the generation of a byproduct comprising copper from the photoresist composition during the etching process using the photoresist material layer as a mask.

As to claim 16, Garaza et al as evidenced by Rahman et al teach that the photoresist or the novolak resin composition includes three of more materials (col.3, lines 8-10 of Rahman et al).

As to claim 17, since the second layer composition is exactly same as the instant invention, the claimed range of the etching time is an inherent property of the composition layer.

As to claim 18, Garaza et al teach that the photoresist is baked on the support layer (col.7, lines 47-52).

8. Claims 1,3,16 and 18 are rejected under 35 U.S.C. 102(b) as being anticipated by Toth (4,243,696).

Toth discloses a product including a first layer (15) and non-patterned second layer or uncured coating (28) composed of a mixture of multiple material disposed entirely over the first layer, wherein the multiple materials comprises both a polymer and particles containing silicon carbide, alumina, silica sand, glass, quartz or mixture thereof (col.2, lines67-col.3, lines 9, lines 59-65 and col.5, lines 3-20).

Toth teaches that the mixture of the multiple material inherently generate byproducts comprising silicon or alumina because they are the constituents of the second material layer, which is backed to be cure (col.3, lines 59-64).

It is noted that the intended use of the product such as "for being handled by the semiconductor manufacturing equipment" is not given patentable weight. See MPEP 2114.

Art Unit: 1765

Claim Rejections - 35 USC § 103

9. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

- (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 10. This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).
- 11. Claims 3 and 19 are rejected under 35 U.S.C. 103(a) as being unpatentable over Garaza et al (6,081,659) as evidenced by Rahman et al (5,521,052).

Garaza et al as evidenced by Rahman et al discussed above in the paragraph 7 but fail to explicitly teach that the ratio of the multiple materials in the mixture corresponds to an exposed area on the standard wafer being simulated.

Garaza et al teach that the photoresist is exposed to produce a pattern on the semiconductor substrate (col.8, lines 32-39).

So, it would have been obvious that the ratio of the multiple materials in the mixture corresponds to an exposed area on the wafer to be simulated because the ratio

Art Unit: 1765

of the photoresist composition is maintained in such that the composition having an extreme low level of metal ions as taught by Rahman et al.

Conclusion

12. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Shamim Ahmed whose telephone number is (571) 272-1457. The examiner can normally be reached on M-Thu (7:00-5:30) Every Friday Off.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nadine G. Norton can be reached on (571) 272-1465. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Art Unit: 1765

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Shamim Ahmed Primary Examiner Art Unit 1765

SA April 14, 2005